

LF253, LF353

Wide bandwidth dual JFET operational amplifiers

Features

- Low power consumption
- Wide common-mode (up to V_{CC}⁺) and differential voltage range
- Low input bias and offset current
- Output short-circuit protection
- High input impedance JFET input stage
- Internal frequency compensation
- Latch up free operation
- High slew rate 16 V/µs (typical)

Description

These circuits are high speed JFET input dual operational amplifiers incorporating well matched, high voltage JFET and bipolar transistors in a monolithic integrated circuit.

The devices feature high slew rates, low input bias and offset currents, and low offset voltage temperature coefficient.



1 Schematics



Figure 1. Schematic diagram (each amplifier)



2 Absolute maximum ratings and operating conditions

Symbol	Parameter	Value	Unit V	
V _{CC}	Supply voltage ⁽¹⁾	±18		
Vi	Input voltage ⁽²⁾	±15	V	
V _{id}	Differential input voltage ⁽³⁾	±30	V	
R _{thja}	Thermal resistance junction to ambient ⁽⁴⁾ SO-8 DIP8	125 85	°C/W	
R _{thjc}	Thermal resistance junction to case ⁽⁴⁾ SO-8 DIP8	40 41	°C/W	
	Output short-circuit duration ⁽⁵⁾	Infinite		
T _{stg}	Storage temperature range	-65 to +150	°C	
	HBM: human body model ⁽⁶⁾	1	kV	
ESD	MM: machine model ⁽⁷⁾	200	V	
	CDM: charged device model ⁽⁸⁾	1.5	kV	

Table 1. Absolute maximum ratings

1. All voltage values, except differential voltage, are with respect to the zero reference level (ground) of the supply voltages where the zero reference level is the midpoint between V_{CC}^+ and V_{CC}^- .

2. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 volts, whichever is less.

- 3. Differential voltages are the non-inverting input terminal with respect to the inverting input terminal.
- 4. Short-circuits can cause excessive heating and destructive dissipation. Values are typical.
- 5. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded
- Human body model: a 100 pF capacitor is charged to the specified voltage, then discharged through a 1.5 kΩ resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are floating.
- 7. Machine model: a 200 pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 Ω). This is done for all couples of connected pin combinations while the other pins are floating.
- 8. Charged device model: all pins and the package are charged together to the specified voltage and then discharged directly to the ground through only one pin. This is done for all pins.

Symbol	Parameter	LF253	LF353	Unit
V _{CC}	Supply voltage	6 to	36	V
T _{oper}	Operating free-air temperature range	-40 to +105	0 to +70	°C

Table 2. Operating conditions



3 Electrical characteristics

Symbol	Parameter	Min.	Тур.	Max.	Unit
V _{io}	Input offset voltage ($R_s = 10k\Omega$) $T_{min} \le T_{amb} \le T_{max}$		3	10 13	mV
DVio	Input offset voltage drift		10		µV/°C
l _{io}	Input offset current ⁽¹⁾ $T_{min} \le T_{amb} \le T_{max}$		5	100 4	pA nA
I _{ib}	Input bias current ⁽¹⁾ $T_{min} \le T_{amb} \le T_{max}$		20	200 20	pA nA
A _{vd}	Large signal voltage gain ($R_L = 2k\Omega$, $V_o = \pm 10V$) $T_{min} \le T_{amb} \le T_{max}$	50 25	200		V/mV
SVR	Supply voltage rejection ratio ($R_S = 10k\Omega$) $T_{min} \le T_{amb} \le T_{max}$	80 80	86		dB
I _{CC}	Supply current, no load T _{min} ≤ T _{amb} ≤ T _{max}		1.4	3.2 3.2	mA
V _{icm}	Input common mode voltage range	±11	+15 -12		V
CMR	Common mode rejection ratio ($R_S = 10k\Omega$) $T_{min} \le T_{amb} \le T_{max}$	70 70	86		dB
I _{OS}	Output short-circuit current $T_{min} \leq T_{amb} \leq T_{max}$	10 10	40	60 60	mA
±V _{opp}	$\begin{array}{l} Output \mbox{ voltage swing} \\ R_L = 2k\Omega \\ R_L = 10k\Omega \\ T_{min} \leq T_{amb} \ \leq T_{max} \\ R_L = 2k\Omega \\ R_L = 10k\Omega \end{array}$	10 12 10 12	12 13.5		v
SR	Slew rate, $V_i = 10V$, $R_L = 2k\Omega$, $C_L = 100pF$, unity gain	12	16		V/µs
t _r	Rise time, $V_i = 20$ mV, $R_L = 2$ k Ω , $C_L = 100$ pF, unity gain		0.1		μs
K _{ov}	Overshoot, $V_i = 20mV$, $R_L = 2k\Omega$, $C_L = 100pF$, unity gain		10		%
GBP	Gain bandwidth product, f = 100kHz, V_{in} = 10mV, R_L = 2k Ω , C_L = 100pF	2.5	4		MHz
R _i	Input resistance		10 ¹²		Ω
THD	Total harmonic distortion, f= 1kHz, A _v = 20dB, R _L = 2kΩ, C _L =100pF, V_0 = 2V _{pp}		0.01		%
e _n	Equivalent input noise voltage $R_S = 100\Omega$, f = 1KHz		15		<u>nV</u> √Hz
Øm	Phase margin		45		Degrees
V _{o1} /V _{o2}	Channel separation ($A_v = 100$)		120		dB

Table 3. Electrical characteristics at $V_{CC} = \pm 15 \text{ V}$, $T_{amb} = \pm 25^{\circ}\text{C}$ (unless otherwise specified)

1. The input bias currents are junction leakage currents which approximately double for every 10°C increase in the junction temperature.





Figure 4. Maximum peak-to-peak output voltage versus frequency

















Figure 8. Input bias current versus free air temperature



Large signal differential voltage

amplification versus free air temp.



Figure 10. Large signal differential voltage



Figure 12.Supply current per amplifier versusFigure 13.Supply current per amplifier versusfree air temperaturesupply voltage



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Figure 18. Total harmonic distortion versus frequency





4 Parameter measurement information





5 Typical application



Figure 21. Quadruple oscillator



6 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.



6.1 DIP8 package information





Table 4. DIP8 package mechanical data

	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
A			5.33			0.210
A1	0.38			0.015		
A2	2.92	3.30	4.95	0.115	0.130	0.195
b	0.36	0.46	0.56	0.014	0.018	0.022
b2	1.14	1.52	1.78	0.045	0.060	0.070
с	0.20	0.25	0.36	0.008	0.010	0.014
D	9.02	9.27	10.16	0.355	0.365	0.400
E	7.62	7.87	8.26	0.300	0.310	0.325
E1	6.10	6.35	7.11	0.240	0.250	0.280
е		2.54			0.100	
eA		7.62			0.300	
eB			10.92			0.430
L	2.92	3.30	3.81	0.115	0.130	0.150



6.2 SO-8 package information





Table 5. SO-8 package mechanical data

	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
А			1.75			0.069
A1	0.10		0.25	0.004		0.010
A2	1.25			0.049		
b	0.28		0.48	0.011		0.019
С	0.17		0.23	0.007		0.010
D	4.80	4.90	5.00	0.189	0.193	0.197
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
е		1.27			0.050	
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
L1		1.04			0.040	
k	1°		8°	1°		8°
CCC			0.10			0.004



7 Ordering information

Table 6. Order codes

Order code	Temperature range	Package	Packing	Marking
LF253N		DIP8	Tube	LF253N
LF253D LF253DT	-40°C, +105°C	SO-8	Tube or Tape & reel	253
LF353N		DIP8	Tube	LF353N
LF353D LF353DT	0°C, +70°C	SO-8	Tube or Tape & reel	353



8 Revision history

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Date	Revision	Changes
01-Mar-2001	1	Initial release.
08-Sep-2008	2	Updated document format. Removed information concerning military temperature range (LF153). Added L1 parameter dimensions in <i>Table 5: SO-8 package</i> <i>mechanical data</i> .
25-Mar-2010	3	Corrected error in <i>Table 6: Order codes</i> : LF253N, LF253D, LF353N and LF353D proposed in tube packing.



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